

Z23

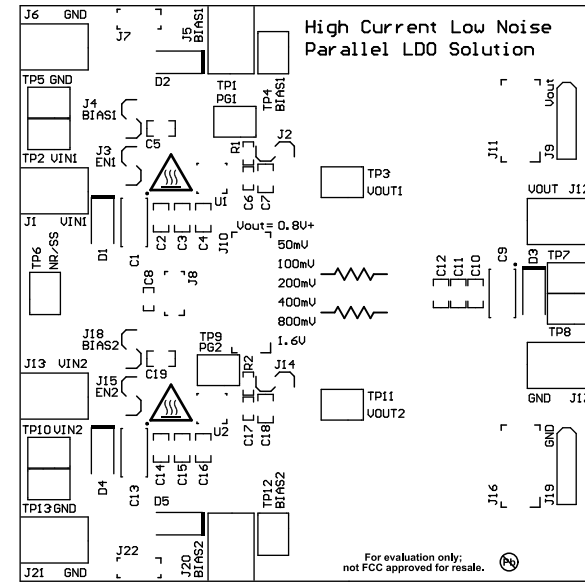
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Z22

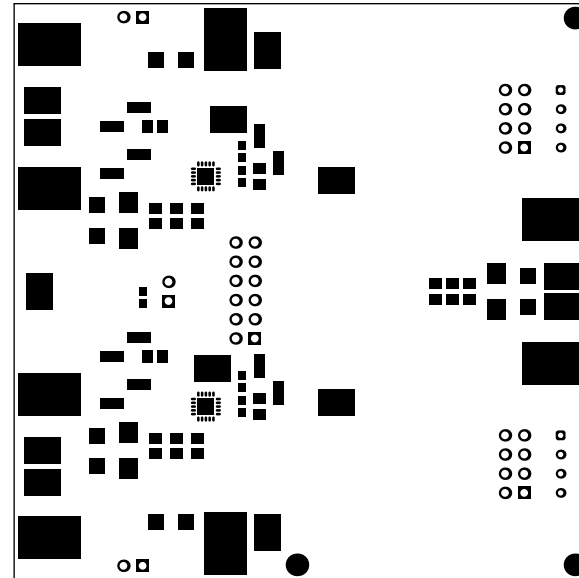
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

Z21

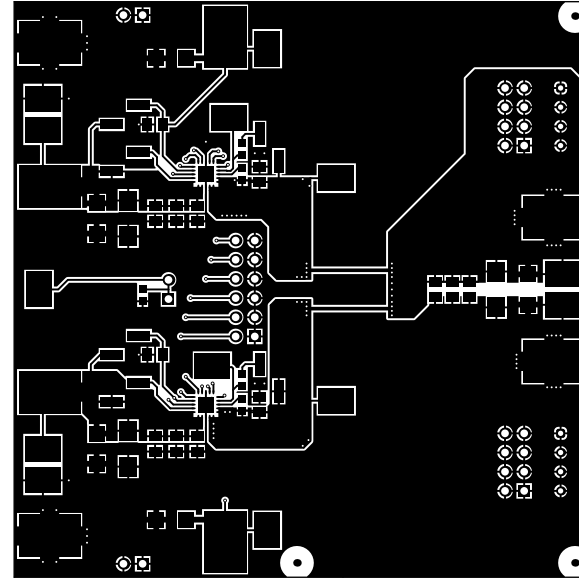
These assemblies are ESD sensitive, ESD precautions shall be observed.



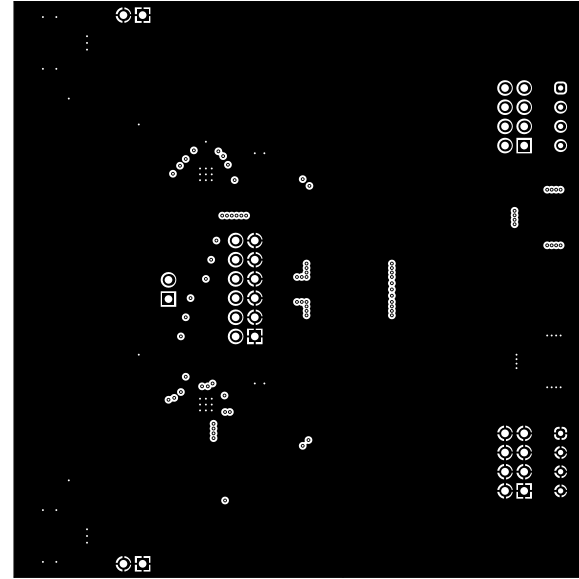
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01232	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: A-01232		
PLOT NAME = Top Overlay	GENERATED : 7/7/2017 9:06:12 AM		TEXAS INSTRUMENTS



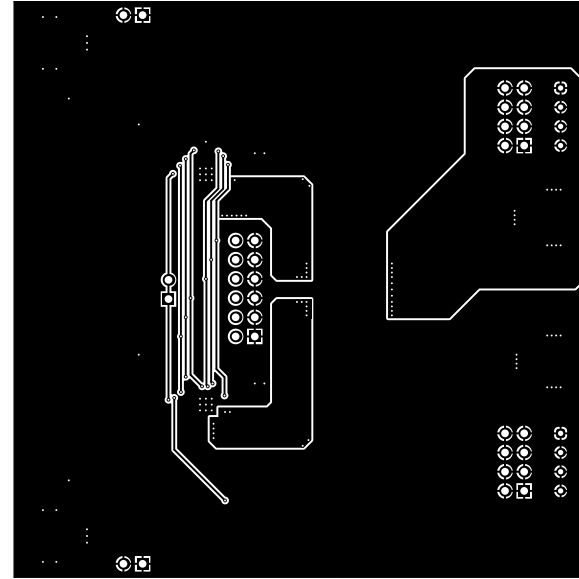
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01232	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: A-01232		
PLOT NAME = Top Solder Mask	GENERATED : 7/7/2017	9:06:13 AM	TEXAS INSTRUMENTS



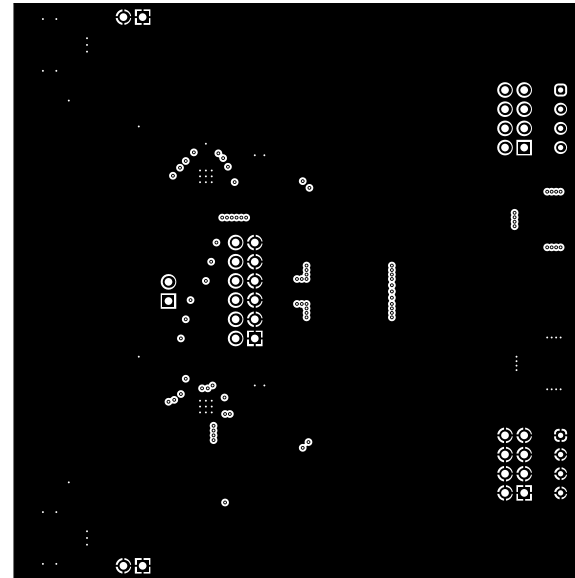
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01232	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: A-01232		
PLOT NAME = Top Layer	GENERATED : 7/7/2017	9:06:14 AM	TEXAS INSTRUMENTS



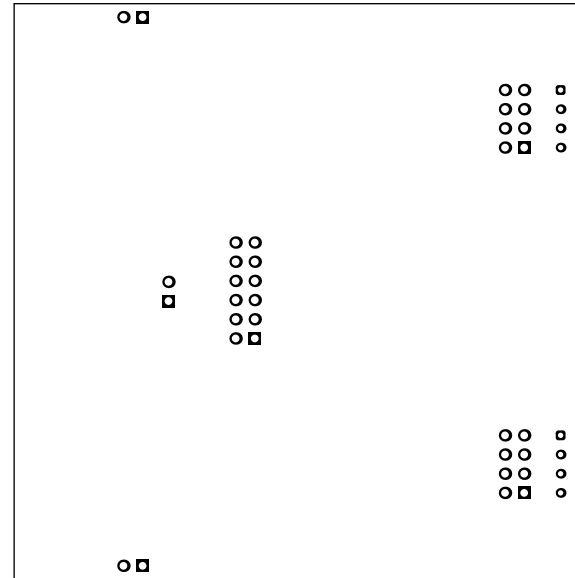
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01232	REV: B	SUN REV: Not In VersionControl
LAYER NAME =	TID #: A-01232		
PLOT NAME = Signal Layer 1	GENERATED : 7/7/2017	9:06:15 AM	TEXAS INSTRUMENTS



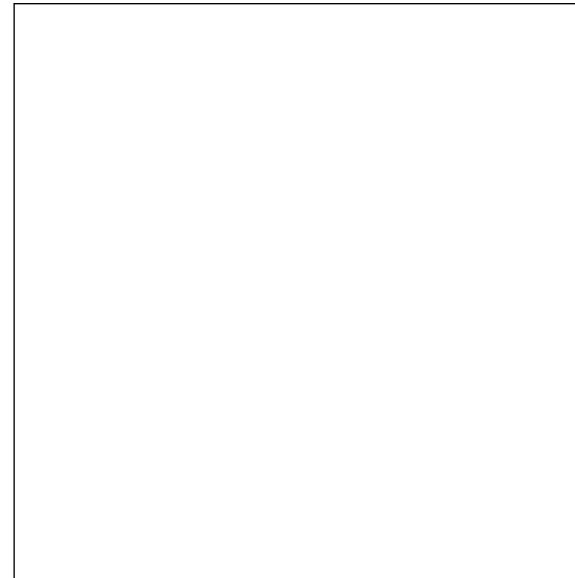
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01232	REV: B	SUN REV: Not In VersionControl
LAYER NAME =	TID #: A-01232		
PLOT NAME = Signal Layer 2	GENERATED : 7/7/2017	9:06:16 AM	TEXAS INSTRUMENTS



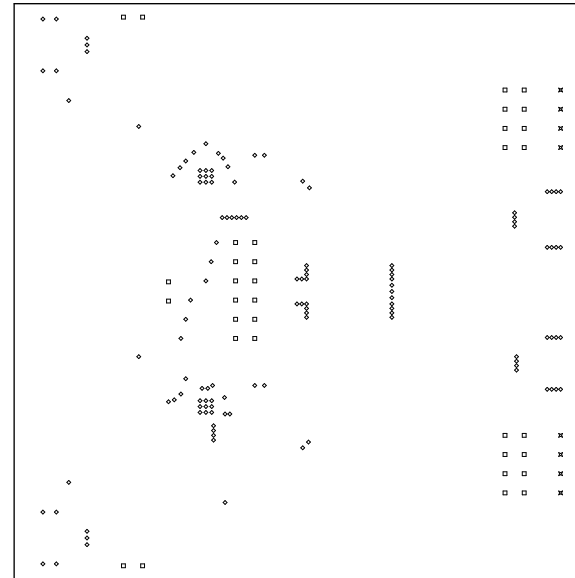
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01232	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: A-01232		
PLOT NAME = Bottom Layer	GENERATED : 7/7/2017	9:06:17 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01232	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: A-01232		
PLOT NAME = Bottom Solder Mask	GENERATED : 7/7/2017 9:06:18 AM	TEXAS INSTRUMENTS	

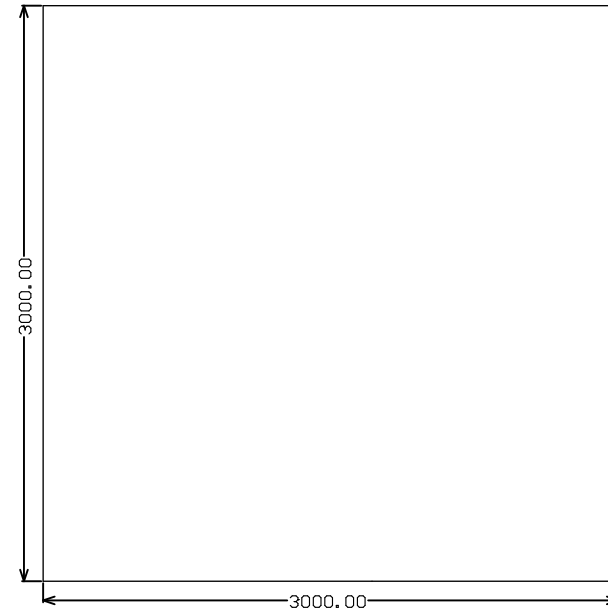


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01232	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: A-01232		
PLOT NAME = Bottom Overlay	GENERATED : 7/7/2017	9:06:19 AM	TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
◇	127	10,00mil (0,254mm)	PTH	Round
⊠	8	27,56mil (0,700mm)	PTH	Round
□	34	40,16mil (1,020mm)	PTH	Round
169 Total				

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01232	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: A-01232		
PLOT NAME = Drill Drawing	GENERATED : 7/7/2017	9:06:21 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01232	REV: B	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: A-01232		
PLOT NAME = Board Dimensions	GENERATED : 7/7/2017	9:06:22 AM	TEXAS INSTRUMENTS

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